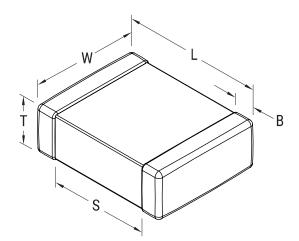


C1812X102F2TAC7210

SMD Comm X8G HT150C Flex, Ceramic, 1,000 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Time is 1000 Hours

100 GOhms

	Specifications	
	Capacitance	1,000 pF
ר+/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
n +/-0.3mm	Tolerance	1%
/-0.10mm	Voltage DC	200 VDC
n MIN	Dielectric Withstanding Voltage	500 VDC
ר+/-0.35mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
30mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

Insulation Resistance

 Dimensions

 Chip Size
 1812

 L
 4.5mm +/-0.4mm

 W
 3.2mm +/-0.3mm

 T
 1mm +/-0.10mm

 S
 2.3mm MIN

 B
 0.7mm +/-0.35mm

Packaging Specifications Packaging

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

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